

KOH-Etching of the Curved Electrode of an In-plane Moving Edge Actuator

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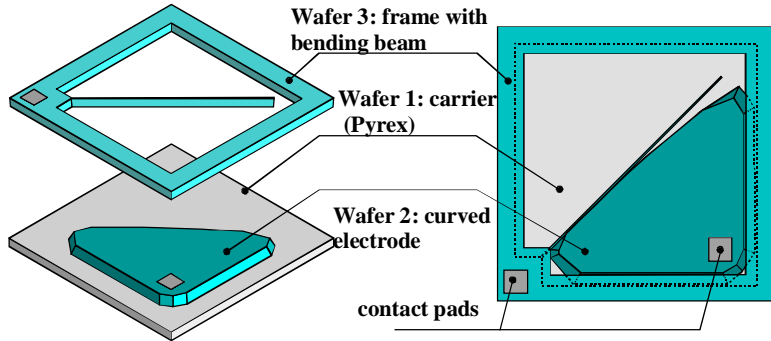
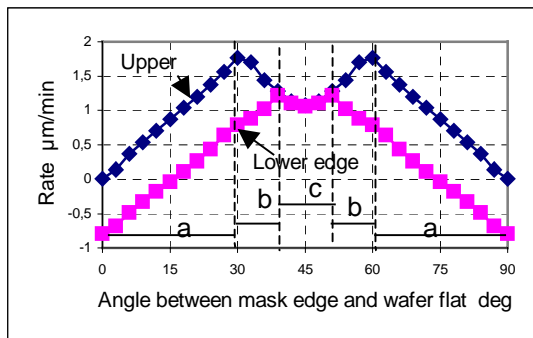


Fig. 1: Concept of the moving edge actuator

Fig. 1 shows the concept of the electrostatic moving edge actuator. The in-plane curved electrode is made by anisotropic KOH etch technique. This etchant generates vertical sidewalls along the $\langle 100 \rangle$ -mask edges so that a thin beam (width: wafer thickness) for the in-plane bending can be produced. In addition nearly

vertical sidewalls are also generated along mask edges deviating about $\pm 4^\circ$ from the $\langle 100 \rangle$ -orientation. An indication that vertical sidewalls occur is the equality of etch rates for their upper and lower edges (fig. 2). Therefore a vertical structure can be etched having a curved contour.

The mask of the curved electrode is realized by using a modified triangular structure. The hypotenuse is replaced by segments of a polygon. The design problem consists in finding the mask polygon from which the resulting course of vertical sidewalls fits equation (1).



$$y = d_{\max} \left(\frac{x}{L} \right)^n \quad (d_{\max} : \text{maximum possible deflection, } L : \text{length of curved electrode}) \quad (1)$$

Fig. 2: Etch rates as functions of the angle α between the direction of the mask edge and the flat of a $\{100\}$ -wafer. a: sidewalls with inclination of about 55° ; b: sidewalls consisting of two facettes; c: nearly vertical sidewalls

At first the curve of equation (1) is approximated by a polygon with an angle increment of $\Delta\alpha = 0,1^\circ$. The mask is constructed by the displacement of the segments of the polygon by the distances of underetching corresponding to their direction $= 45^\circ - \Delta\alpha$ and to the etching time. The underetch rates of KOH 30% 80°C are known for all directions of mask edges in steps of $\Delta\alpha = 3^\circ$ (file of etchant of simulator SIMODE). By a parabolic interpolation between 41° and 49° we can use $v(45 \pm \Delta\alpha) = (0,00555\Delta\alpha^2 + 1,0775) \mu\text{m}/\text{min}$ (2) to calculate the rates in steps of $\Delta\alpha = 0,1^\circ$ (equation (2) fits the rates of fig. 2 in region c).

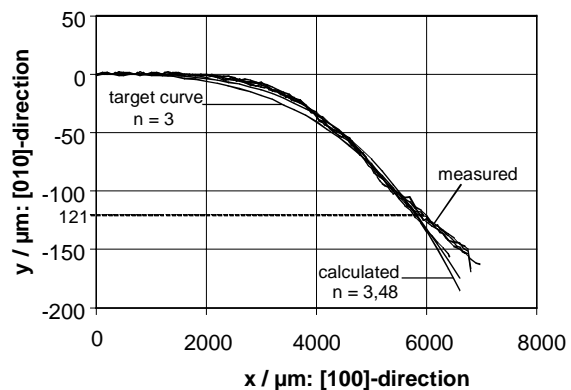
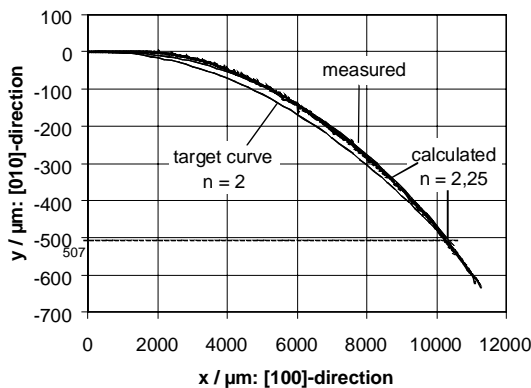


Fig. 3: Measured contours of curved electrodes

An example of the measured contours of the realized curved counter electrode is shown in fig. 3. The best fits were found with the exponents $n = 2,25$ and $n = 3,48$ which exceed a little the target values of $n = 2$ and $n = 3$, respectively. This indicates the realizability of sidewalls with a defined curved course. The deviations arise from the inaccuracy of the etch rates.